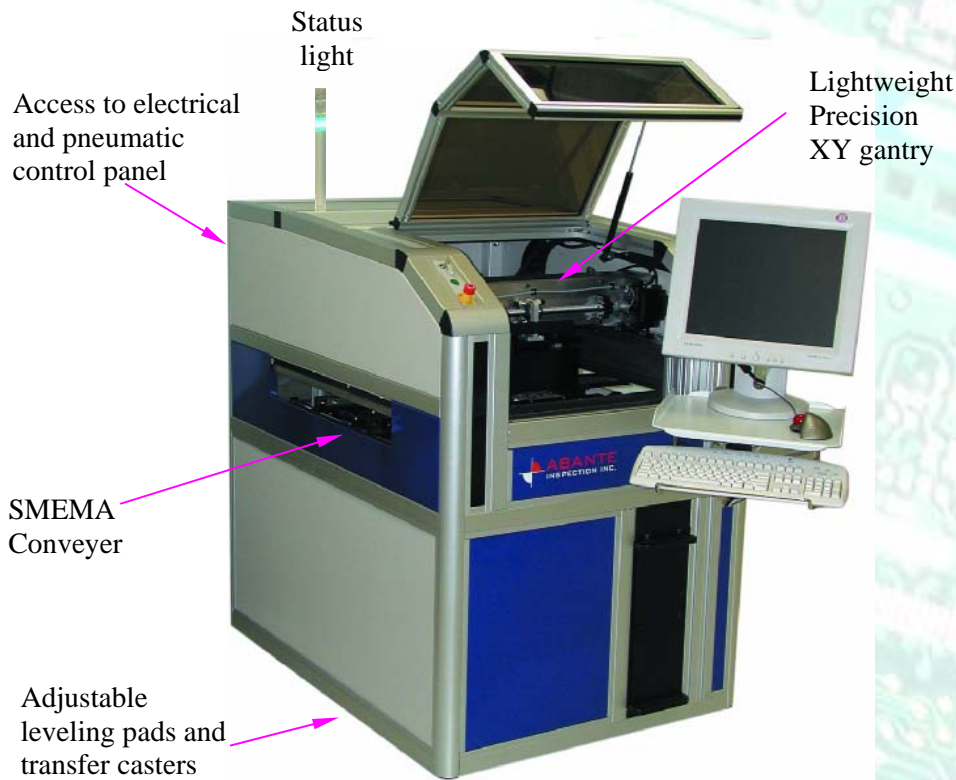


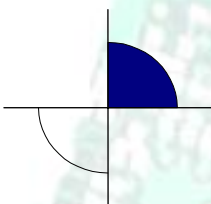
# AI-816SC

FC Substrate Bump Inspection System



- **High speed – high accuracy 3D and 2D in-line inspection at production speed**

- Fully static 3D laser technology with 2D color for highly reliable measurements and defect detection
- Panel and JEDEC tray capability
- Easy to use set-up screen and reliable operation
- Accurate height, position, area and volume measurements
- Small footprint
- Tray handling and part sorting optional



**Aceris 3D**  
INSPECTION INC.

Flip Chip Substrate Inspection

